

L Number	Hits	Search Text	DB	Time stamp
-	2	6517894.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 14:34
-	84	204/269.ccls. and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 14:36
-	1	204/269.ccls. and substrate AND pit	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 14:39
-	1	204/269.ccls. and substrate AND pits	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 14:41
-	525	204/\$.ccls. AND pits	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 14:42
-	25	204/\$.ccls. AND pits AND electroplat\$3 near10 layers	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 14:49
-	380	204/\$.ccls. AND pit AND layer	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:08
-	64	204/\$.ccls. AND pit AND layer AND electroplat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 14:50
-	10549	plat\$3 AND pit AND layer	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:09
-	1	(plat\$3 AND pit AND layer AND substrate) AND 118/423.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:10
-	6405	plat\$3 AND pit AND layer AND substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:15
-	65787	plat\$3 AND pit AND layer AND substrate 204/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:15
-	187	plat\$3 AND pit AND layer AND substrate AND 204/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:33
-	235	204/267.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:35
-	39	204/267.ccls. AND substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:38
-	3	204/267.ccls. AND substrate AND pit	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:40
-	65353	first adj layer same second adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:50

-	3656	first adj layer same second adj layer NEAR25 different	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:47
-	32	(first adj layer same second adj layer NEAR25 different) and 118/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 15:47
-	6	first adj layer same second adj layer AND 204/206.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 16:10
-	0	first adj layer same second adj layer SAME pit NEAR substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 16:13
-	17	first adj layer same second adj layer SAME pit NEAR10 substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 16:15
-	109	first adj layer same second adj layer SAME pit	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 16:20
-	0	first adj layer same second adj layer SAME pit AND 204/\$.ccls. and 205/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 16:25
-	793	wire near10 pits	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 16:26
-	4	(wire near10 pits) and memory adj device	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/22 16:27